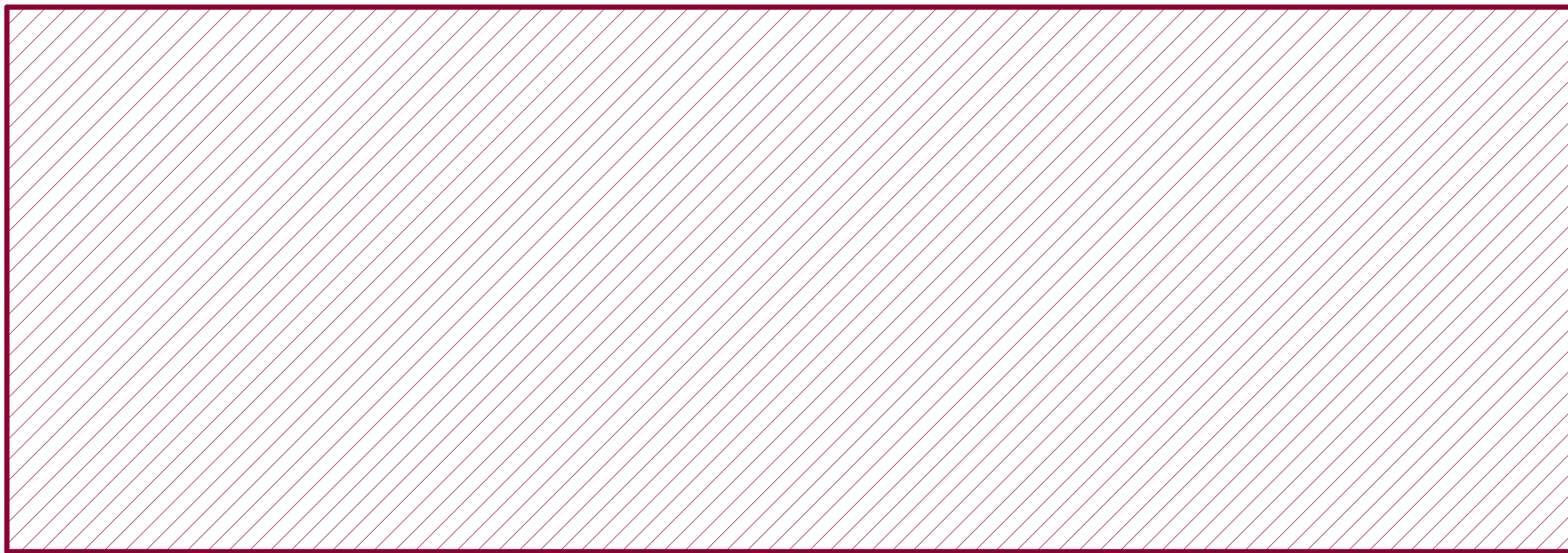


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer	CF-004	1.38mil		
	Dielectric 2	2116, 2113	8.60mil	4.3	
2	GND	CF-004	1.38mil		
	Dielectric 1	FR-4	39.00mil	4.8	
3	VCC	CF-004	1.38mil		
	Dielectric 3	2116, 2113	8.60mil	4.3	
4	Bottom Layer	CF-004	1.38mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
☆	4	45.00mil (1.143mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v160h114m160_503323056			
⊕	4	125.00mil (3.175mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c318hn318			
○	8	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c152h76			
⊗	8	125.00mil (3.175mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)			
□	16	62.21mil (1.580mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c254h158			
⊗	40	18.00mil (0.457mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c46hn46m46			
▽	248	13.00mil (0.330mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)			
	328 Total										

